

WHAT IS CLAIMED IS:

1. A method for installation of a temperature-sensitive electronic component on a board comprising:
 - providing a board which has openings for solder connections on an electronic component to pass through,
 - providing a removable protection apparatus to protect the component during the installation process,
 - moving the component first so close to the board that the solder connections project through the openings in the board,
 - connecting the solder connections using a soldering method to a conductor track which is provided on a side of the board which faces away from the component, and
 - subsequently removing the protection apparatus once the soldering process has been completed,
 - wherein the component is thermally coupled to the protection apparatus during the soldering process so that some of the heat which is introduced into the solder connections during the soldering process is passed to the protection apparatus.
2. The method as claimed in claim 1, wherein the protection apparatus is thermally coupled to the solder connections of the component during the soldering process.

3. The method as claimed in claim 1, wherein the solder connections of the component are connected to the board by means of wave soldering.

4. The method as claimed in Claim 2, wherein the solder connections of the component are connected to the board by means of wave soldering.

5. A protection apparatus for a temperature-sensitive optoelectronic component, for use during an installation process during which solder connections which are provided on the component are connected to a conductor track which is provided on a side of a board which faces away from the component,

wherein the protection apparatus is configured to be selectively removed from the component,

wherein the protection apparatus comprises a protection sleeve which surrounds at least portions of the component, and

wherein the protection apparatus can be thermally coupled to the component.

6. The protection apparatus as claimed in claim 5, wherein the protection apparatus is configured to be thermally coupled to the solder connections of the component.

7. The protection apparatus as claimed in claim 5, wherein the protection sleeve is configured to provide thermal insulation in an area of its inner wall which faces the component, and has a coating with high thermal conductivity at least in places on its outer wall which faces away from the component.
8. The protection apparatus as claimed in claim 6, wherein the protection sleeve is configured to provide thermal insulation in an area of its inner wall which faces the component, and has a coating with high thermal conductivity at least in places on its outer wall which faces away from the component.
9. The protection apparatus as claimed in claim 5, wherein the protection apparatus is formed by a closed bubble through whose wall the solder connections project.
10. The protection apparatus as claimed in claim 6, wherein the protection apparatus is formed by a closed bubble through whose wall the solder connections project.
11. The protection apparatus as claimed in claim 7, wherein the protection apparatus is formed by a closed bubble through whose wall the solder connections project.

12. The protection apparatus as claim in claim 8, wherein the protection apparatus is formed by a closed bubble through whose wall the solder connections project.
13. The protection apparatus as claimed in claim 5, wherein the protection apparatus has an elastic clip which is connected to the protection sleeve and by means of which, when the protection apparatus is fitted to the component, the protection sleeve can be fixed and thermally coupled with respect to the component, in particular with respect to the solder connections.
14. The protection apparatus as claimed in claim 6, wherein the protection apparatus has an elastic clip which is connected to the protection sleeve and by means of which, when the protection apparatus is fitted to the component, the protection sleeve can be fixed and thermally coupled with respect to the component, in particular with respect to the solder connections.
15. The protection apparatus as claimed in claim 7, wherein the protection apparatus has an elastic clip which is connected to the protection sleeve and by means of which, when the protection apparatus is fitted to the component, the protection sleeve can be fixed and

thermally coupled with respect to the component, in particular with respect to the solder connections.

16. The protection apparatus as claimed in claim 8, wherein the protection apparatus has an elastic clip which is connected to the protection sleeve and by means of which, when the protection apparatus is fitted to the component, the protection sleeve can be fixed and thermally coupled with respect to the component, in particular with respect to the solder connections.

17. The protection apparatus as claimed in claim 9, wherein the wall of the protection apparatus includes an inner layer of thermal insulation which faces the component and an outer coating of high thermal conductant material, said inner layer being bonded to the optoelectronic component with said solder connection protruding through said inner layer and outer coating.

18. A method of making an electronic component assembly comprising:
providing a circuit board with through openings,
placing a temperature sensitive electronic component on one side of the circuit board with solder connection members of the electronic component protruding through respective ones of the through openings,

placing a removable protection apparatus around the electronic component,

soldering the solder connection members to a conductor disposed at a second side of the circuit board opposite the first side,

thermally coupling the component to the protection apparatus during said soldering so as to introduce heat from the soldering process to the protection apparatus, and

removing the protection apparatus after said soldering.

19. A method according to claim 18, comprising thermally coupling the protection apparatus to said solder connection members during said soldering.

20. A method according to claim 18, wherein said soldering is wave soldering.

21. A method according to claim 19, wherein said soldering is wave soldering.

22. A method according to claim 18, wherein said protection apparatus is a bubble formed of a plastic layer facing the component with a metallic coating on the plastic layer facing away from the component, said solder connections in use penetrating the plastic layer with

metallic coating to thereby assure thermal and mechanical coupling of the solder connections with the metallic coating.

23. A method according to claim 22, wherein said removing includes tearing the bubble layer with metallic component along the solder connections member with perforations formed by the solder connections facilitating said removing.

24. A method according to claim 23, wherein said component is bonded to the plastic layer side of the protection apparatus such that the solder connection members pass through the plastic layer and metallic layer and edges of said layers are folded around the components to form a closed bubble.

25. A protection apparatus for use in practicing the method of claim 18.

26. A protection apparatus for use in practicing the method of claim 22.

27. An electronic component assembly made by the method of claim 18.

28. An electronic component assembly made by the method of claim 22.

29. An assembly according to claim 28, wherein said electronic component is an optoelectronic component.

30. A protective assembly for protecting at least one electronic component during soldering operation where the electronic component is placed on a first side of a board with solder connection members fixed to the electronic component and protruding through openings in the board to an opposite side of the board to be there solder connected with a conductor,
wherein said protective assembly is a removable assembly which is configured to be thermally coupled to the at least one electronic component during soldering operations.

31. A protective assembly according to claim 30, wherein said protection apparatus is a bubble formed of a plastic layer facing the component with a metallic coating on the plastic layer facing away from the component, said solder connections in use penetrating the plastic layer with metal coating to thereby assure thermal and mechanical coupling of the solder connections with the metallic coating.

32. A protection assembly according to claim 31, wherein said component is bonded to the plastic layer side of the protection apparatus such that the solder connection members pass through the plastic layer and metallic layer and edges of said layers are folded around the components to form a closed bubble.